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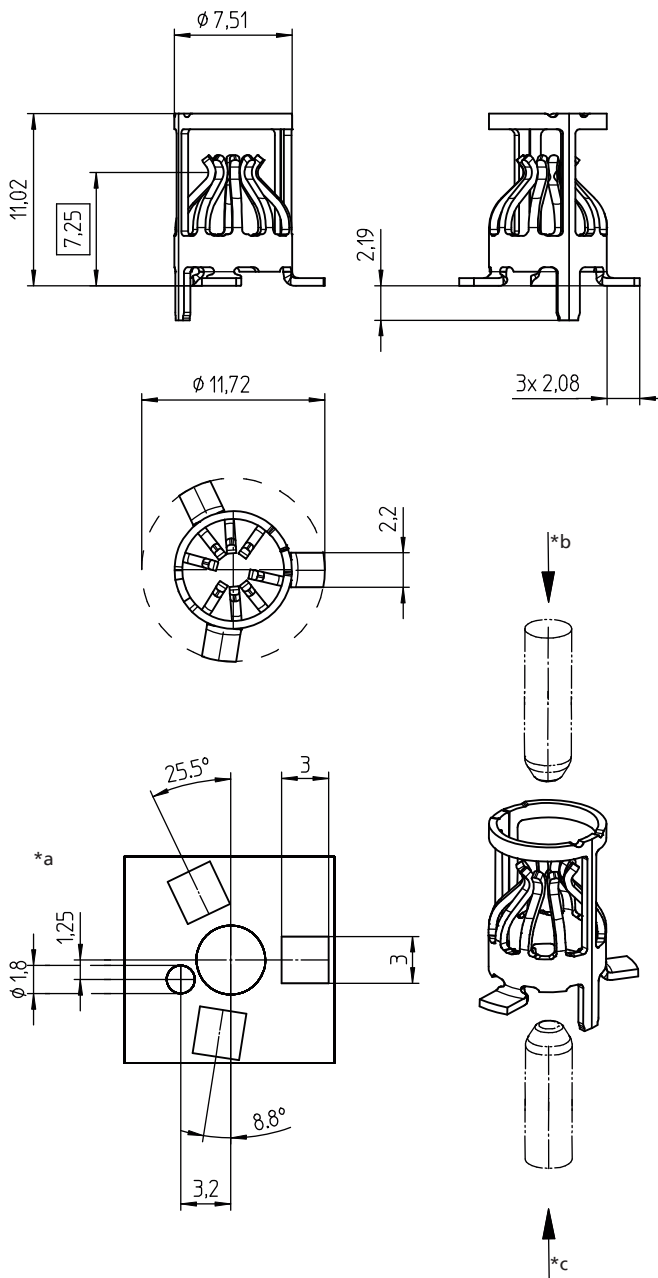
High-current contact elements



High-current contact bush, in surface mount technology (SMT), for pin contacts 3.0–4.0 mm, for printed circuit boards or busbars

State: New, under preparation

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Environmental conditions

Temperature range -40 °C/+150 °C

Materials

Contact Cu alloy, tin/silver-plated

Mechanical data

Mating with round pin contact, diameter 3–4 mm
applicable for reflow soldering on printed circuit board
applicable for laser welding on a busbar or lead frame

Mating cycles ≤ 5

Insertion force 30 N ± 12 N – top entry
32 N ± 12 N – bottom entry

Withdrawal force 19 N ± 7 N

Electrical data (at T_{amb} 20 °C)

Contact resistance < 0.5 mΩ

Rated current 115 A¹

¹ depending on the connection to the printed circuit board/busbar, installation situation and heat dissipation

*a printed circuit board layout, components side view

*b mating from top direction

*c mating from bottom direction

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Designation	Pole Number	PU (Pieces)	MDQ (Pieces)
458501	1		

Packaging:

on reel